PCN Number:	20181011000.1	PCN Date:	Oct 15, 2018
Title:	Qualification of RFAB as an additional Wafer Fab Site option for select devices in HPA07 Technology		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jan 15, 2019	Estimated Sample Availability:	Date provided at sample request.

Change Type:					
☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☒	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in "Product Affected" section.

Current Sites			Additional Sites		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DP1DM5	HPA07	200mm	RFAB	HPA07	300mm
AIZU	HPA07	200mm			

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
AIZU	CU2	JPN	Aizuwakamatsu-shi

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)

Product Affected Group:

DRV401AIDWP	DRV401AIDWPRG4	DRV401AIRGWT	DRV401AIRGWTG4
DRV401AIDWPR	DRV401AIRGWR		

Qualification Report
RFAB G4DRV401GAP offload from Aizu DRV401AIRGWR
Approve Date 28-Sept-2018
Product Attributes

Attributes	Qual Device: DRV401AIRGWR	Process QBS Device: CD3232A1YFFR -	Package QBS Device: DRV401AIRGWR	Package QBS Device: BQ24196RGER
Wafer Fab Supplier	RFAB	RFAB	Aizu	RFAB
Wafer Process	HPA07	HPA07	HPA07	LBC7
Assembly Site	CDAT	JCAP	CDAT	CDAT
Package Type	VQFN	WCSP	VQFN	WSON
Package Designator	RGW	YFF	RGW	DRV

- Qual Devices qualified at LEVEL2-260CG: DRV401AIRGWR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DRV401AIRGWR	Process QBS Device: CD3232A1YFFR -	Package QBS Device: DRV401AIRGWR	Package QBS Device: BQ24196RGER
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	3/231/0	-	-
AC	Autoclave 121C	96 Hours	-	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0	3/231/0	-
HTOL	Life Test, 125C	1000 Hours	2/154/0	3/231/0	-	-
ELFR	Early Life Failure Rate, 150C	24 Hours	-	3/2400/0	-	-
HBM	ESD - HBM	1500 V	1/3/0	3/9/0	-	-
HBM	ESD - HBM	1000 V	1/3/0	-		
CDM	ESD - CDM	1000 V	1/3/0	3/9/0	--	
LU	Latch-up	(Per AEC Q100-004)	1/6/0	3/18/0	-	-
ED	Electrical Distributions	Cpk>1.67 Room, Hot, & Cold Test	1/30/0	3/90/0	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	-	-
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass	Pass	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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